

UF 1230

Low Coefficient of Thermal Expansion Epoxy Underfill

| Typical Properties | | | |
|---|-------------|----------------------------|------------------|
| Property | Unit | Value | Test Method |
| Color of Component | | Blue | Visual |
| Density | Gram /cc | 1.67 | ASTM D792 |
| Viscosity at 25°C | cps | 8,000 | ASTM D2196 |
| Property as Cured | | | |
| Color | | Blue | Visual |
| Young's modulus | GPa | 7.6 | DMA |
| Dielectric Constant | @1000Hz | 3.5 | ASTM D150 |
| Dielectric Strength | Volt/mil AC | > 500 | ASTM D149 |
| Volume Resistivity | Ohm-cm | > 10E+14 | ASTM D257 |
| Coefficient of Thermal Expansion | ppm/C | 75 (@ > Tg) 19 (@ < Tg) | IPC-TM-650 |
| Adhesion (Al/Al lap shear) | Psi | > 1800 | ASTM D1002 |
| Tg | °C | 150 | DMA |
| Temperature Usage | °C | -80 to 200 | TGA |
| Cure Profile | | | |
| Cure at 115°C | min | 50 | Durometer |
| Cure at 125°C | min | 25 | Durometer |
| Cure at 150°C | min | 15 | Durometer |
| Pot / Work Life at 25°C (after warmed up) | hr | 24 | Viscosity double |

These figures are only intended as a guide and should not be used in preparing specifications.

Characteristics

UF 1230 is an epoxy-based low coefficient of thermal expansion (CTE) adhesive for underfilling or encapsulating chip-on-board, bare die, BGA, flip-chip, CSP, and other electronic applications. It is a one-part, capillary flow formulation that cures at elevated temperature to provide strong bonding to silicon, flip chip, BGA, ceramics, FR4, LTCC, aluminum, copper, stainless steel, etc. with minimized thermal mismatching stress. The very low CTE formulation provides better thermal cycle performances. UF 1230 is dispensable. For underfilling, it is recommended to warm the applied surface to ~ 105°C to promote faster capillary flow.

Special Features and Benefits

- Low CTE for stress compliance
- Fast flow and capillary flow
- High thermal stability
- High structural bonding strength
- Low bleeding, low volatile
- Low ionic content

Typical Applications

- Aerospace electronics
- Automotive electronics
- Semiconductor and Telecommunications
- Bonding of die to LTCC, Al, Cu
- Underfilling of BGA, Bare die, flip-chip, CSP
- Chip-on-board bonding / encapsulating

UF 1230 has a shelf life of at least 3 months when stored in freezer (-40°C) in the originally sealed container.

Processing Instruction

The adhesive is a pre-mixed adhesive as one part for easier applying. In order to keep longer usage life, please always store the original or left material in freezer (-40°C). For some applications, it is recommended to warm the applied surface to ~ 105°C, and/or the adhesive to about 50°C, to promote faster capillary flow.

We recommend running preliminary tests to optimize conditions for the particular application. Comprehensive processing instructions can be obtained by contacting directly to United Adhesives, Inc.

UF 1230 has a shelf life of at least 3 months when stored in freezer (-40°C) in the originally sealed container. The 'Best use before end' date of each batch appears on the product label. Storage beyond the date specified on the label does not necessarily mean that the product is no longer usable. In this case however, the properties required for the intended use must be checked for quality assurance reasons.

Safety information

General hygiene regulations should be observed. Comprehensive instructions are given in the corresponding Material Safety Data Sheets. They are available on request from United Adhesives, Inc.

The data presented in this leaflet are in accordance with the present state of our knowledge, but do not absolve the user from carefully checking all supplies immediately on receipt. We reserve the right to alter product constants within the scope of technical progress or new developments. The recommendations made in this leaflet should be checked by preliminary trials because of conditions during processing over which we have no control, especially where other companies' raw materials are also being used. The recommendations do not absolve the user from the obligation of investigating the possibility of infringement of third parties' rights and, if necessary, clarifying the position. Recommendations for use do not constitute a warranty, either express or implied, of the fitness or suitability of the products for a particular purpose. For technical, quality, or product safety questions, please contact directly to United Adhesives Inc.